# VS-HFA08TA60CSPbF

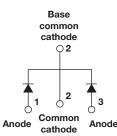
Vishay Semiconductors

HALOGEN

### HEXFRED<sup>®</sup> Ultrafast Soft Recovery Diode, 2 x 4 A



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PRODUCT SUMMARY							
Package	TO-263AB (D <sup>2</sup> PAK)						
I <sub>F(AV)</sub>	8 A						
V <sub>R</sub>	600 V						
V <sub>F</sub> at I <sub>F</sub>	2.2 V						
t <sub>rr</sub> (typ.)	17 ns						
T <sub>J</sub> max.	150 °C						
Diode variation	Common cathode						

### FEATURES

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
   RoHS
   COMPLIANT
- AEC-Q101 qualified
- Material categorization: For definitions of FREE compliance please see <u>www.vishay.com/doc?99912</u>

### BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION

VS-HFA08TA60CSPbF is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 4 A per leg continuous current, the VS-HFA08TA60CSPbF is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED<sup>®</sup> product line features extremely low values of peak recovery current (I<sub>BBM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA08TA60CSPbF is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V <sub>R</sub>		600	V					
Maximum continuous forward current		T <sub>C</sub> = 100 °C	4						
per devic	e I <sub>F</sub>	1C = 100 C	8	А					
Single pulse forward current	I <sub>FSM</sub>		25	~					
Maximum repetitive forward current	I <sub>FRM</sub>		16						
Maximum power dissipation	PD	T <sub>C</sub> = 25 °C	25	w					
	۳D	T <sub>C</sub> = 100 °C	10	vv					
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to + 150	°C					

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<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA		600	-	-			
Maximum forward voltage		I <sub>F</sub> = 4.0 A		-	1.5	1.8	V		
	V <sub>FM</sub>	I <sub>F</sub> = 8.0 A	See fig. 1	-	1.8	2.2			
		I <sub>F</sub> = 4.0 A, T <sub>J</sub> = 125 °C		-	1.4	1.7			
Maximum reverse		V <sub>R</sub> = V <sub>R</sub> rated	Coo fig. 0	-	0.17	3.0			
leakage current	I <sub>RM</sub>	$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$	See fig. 2	-	44	300	μA		
Junction capacitance	CT	V <sub>R</sub> = 200 V	See fig. 3	-	4.0	8.0	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from pa	ackage body	-	8.0	-	nH		

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25$ °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS				
Reverse recovery time See fig. 5, 6 and 16	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200 \text{ A}$	Α/μs, V <sub>R</sub> = 30 V	-	17	-				
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	28	42	ns			
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 4.0 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	38	57				
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	2.9	5.2	A nC			
See fig. 7 and 8	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	3.7	6.7				
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	40	60				
See fig. 9 and 10	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	70	105				
Peak rate of fall of recovery current during t <sub>h</sub>	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	280	-	A/µs			
See fig. 11 and 12	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	235	-	-7,μ5			

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C			
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	5.0	K/W			
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	80	r∨ vv			
Weight			-	2.0	-	g			
weight			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style D <sup>2</sup> PAK	HFA08TA60CS						

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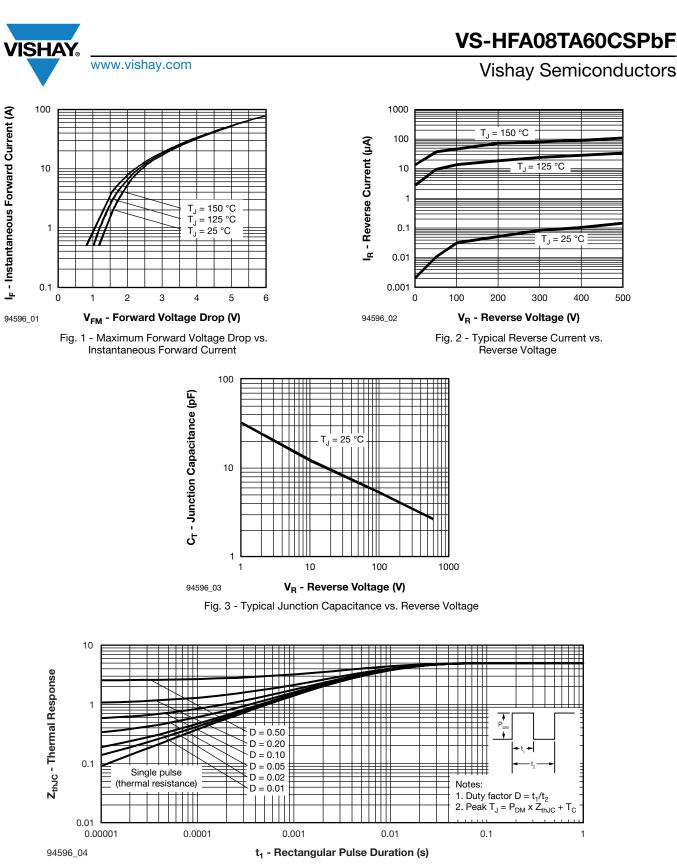


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

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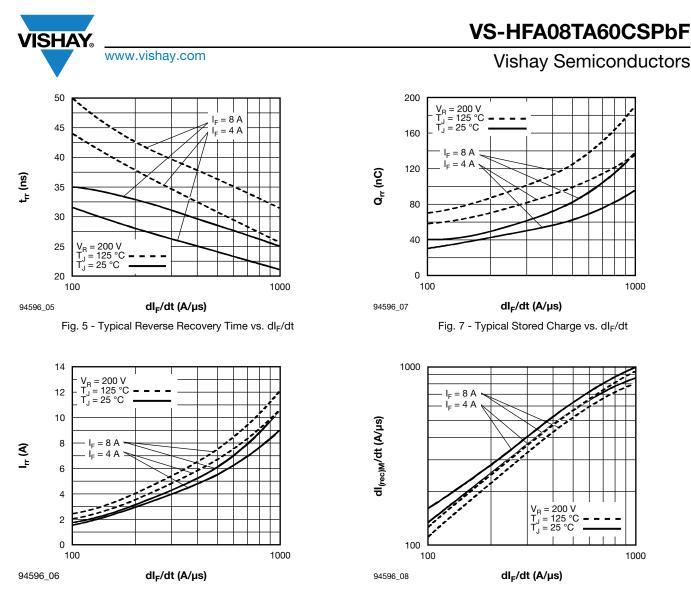


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt

Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$ 





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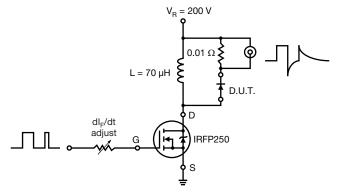
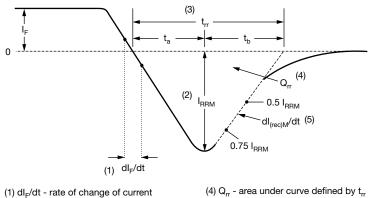


Fig. 9 - Reverse Recovery Parameter Test Circuit



(1) dI<sub>F</sub>/dt - rate of change of current through zero crossing

and I<sub>RRM</sub>

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

- (2) I<sub>RRM</sub> peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75  $I_{\text{RRM}}$  and 0.50  $I_{\text{RRM}}$  extrapolated to zero current.
- (5)  $dI_{(rec)M}/dt$  peak rate of change of current during  $t_b$  portion of  $t_{rr}$
- Fig. 10 Reverse Recovery Waveform and Definitions

### **ORDERING INFORMATION TABLE**

Device code	vs-	HF	Α	08	ТА	60	С	S	TRL	PbF		
		2	3	4	5	6	7	8	9	10		
		<ul> <li>1 - Vishay Semiconductors product</li> <li>2 - HEXFRED<sup>®</sup> family</li> </ul>										
	3 -											
	4 ·	· Cur	rent rati	ng (08 =	= 8 A)							
	5	- Pac	kage ou	utline (T	A = TO-	220, 3	eads)					
	6	· Vol	age rati	ing (60 =	= 600 V)	)						
	7 -	· Circ	uit conf	iguratio	n (C = C	commor	n cathoo	le)				
	8	· S =	D <sup>2</sup> PAK									
	9 -	- • None = Tube										
		<ul> <li>TRL = Tape and reel (left oriented)</li> </ul>										
		<ul> <li>TRR = Tape and reel (right oriented)</li> </ul>										
	10 ·											
		• P	= Lead	(Pb)-fre	e (for D	<sup>2</sup> PAK T	RR and	TRL)				

LINKS TO RELATED DOCUMENTS						
Dimensions	www.vishay.com/doc?95046					
Part marking information	www.vishay.com/doc?95054					
Packaging information	www.vishay.com/doc?95032					

ORDERING INFORMATION (Example)										
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION							
VS-HFA08TA60CSPBF	50	1000	Antistatic plastic tube							
VS-HFA08TA60CSTRRP	800	800	13" diameter reel							
VS-HFA08TA60CSTRLP	800	800	13" diameter reel							

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## **Outline Dimensions**



D<sup>2</sup>PAK

### **DIMENSIONS** in millimeters and inches

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SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIM	IETERS	INC	HES	NOTES	
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTED	STWDUL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing per ASME Y14.5 M-1994

<sup>(2)</sup> Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

<sup>(3)</sup> Thermal pad contour optional within dimension E, L1, D1 and E1

<sup>(4)</sup> Dimension b1 and c1 apply to base metal only

<sup>(5)</sup> Datum A and B to be determined at datum plane H

<sup>(6)</sup> Controlling dimension: inch

<sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> outline TO-263AB

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